PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT3000363

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
MASAHARU MIZUTANI	08/20/2014
MASAO INOUE	08/20/2014
HIROSHI UMEDA	08/18/2014
MASARU KADOSHIMA	08/20/2014

RECEIVING PARTY DATA

Name:	Renesas Electronics Corporation
Street Address:	1753, Shimonumabe, Nakahara-ku,
City:	Kawasaki-shi, Kanagawa
State/Country:	JAPAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14470719

CORRESPONDENCE DATA

Fax Number: (703)610-8686

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: (703)903-9000
Email: ctexidor@milesstockbridge.com
Correspondent Name: MITCHELL W. SHAPIRO
Address Line 1: MILES & STOCKBRIDGE P.C.
Address Line 2: 1751 PINNACLE DRIVE, SUITE 1500
Address Line 4: TYSONS CORNER, VIRGINIA 22102-3833

ATTORNEY DOCKET NUMBER:	XA-12438/T3381-19961US01
NAME OF SUBMITTER:	MITCHELL W. SHAPIRO
SIGNATURE:	/Mitchell W. Shapiro/
DATE SIGNED:	08/28/2014

Total Attachments: 2
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source=Assignment#page2.tif

ASSIGNMENT
（譲 渡 証）

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar ($1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Renesas Electronics Corporation,
a corporation organized under the laws of Japan,
located at 1753, Shimonumabe, Nakahara-ku, Kawasaki-shi, Kanagawa 211-8668, Japan,
receipt of which is hereby acknowledged I do hereby sell and assign to said Renesas Electronics Corporation,
its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURING THE SAME

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,

to be held and enjoyed by said Renesas Electronics Corporation,

its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Renesas Electronics Corporation.

Signed on the date(s) indicated aside our signatures:

	INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1)	Masaharu Mizutani (Masaharu MIZUTANI)	August 20, 2014
2)	Masao Inoue (Masao INOUE)	August 20, 2014
3)	(Hiroshi UMEDA)	
4)	Masaru Kadoshima (Masaru KADOSHIMA)	August 20, 2014
5)		
6)		

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	INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1)	(Masaharu MIZUTANI)	
2)	(Masao INOUE)	
3)	Hiroshi Umeda (Hiroshi UMEDA)	2014-8-18
4)	(Masaru KADOSHIMA)	
5)		
6)		